

ABSTRACT OF THE DISCLOSURE

A flip chip package mainly comprises a chip, a leadless lead frame. The leadless lead frame has a die paddle and a plurality of leads. The active surface of the chip has a plurality of bonding pads formed thereon. Besides, a plurality of bumps formed on the bonding pads are electrically connected to the chip, the leads and the die paddle. Therein, the die paddle electrically connected to the chip via the bumps not only prevents the chip from being dislocated but also provides another grounding and heat transmission paths to enhance the electrical, thermal and mechanical performance of the flip chip package. Similarly, the bumps formed on the bonding pads of the chip are electrically connected to the leads so as to fix the chip to the lead frame more securely.